

'*' indicates required field

? indicates online help

27th Technology Leadership Awards

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Disclaimer

27th Annual PCB Technology Leadership Awards

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Disclaimer response *

Accept

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First name *

Last name *

Email address *

Company name *

Mentor Graphics contact

Design category (Primary) *

Design category (Secondary)

Design name *

End-product description *

Unique features * ?

Critical constraints * ?

Intended use of the submitted design version *

- Proof of concept
- Debug / prototype
- Low-volume production
- High-volume production

Tool flow *

- Xpedition Enterprise
- PADS
- Board Station
- Other

Tools used * ?

Advanced technologies ?

- RF/microwave
- Chip on board
- HDI/microvia
- Buried capacitance
- Flex/rigid-flex
- Flip chip
- Embedded passives
- Embedded actives

Design for... ?

- Signal integrity
- Power integrity
- Fabrication
- Assembly
- Test
- Reliability
- Cost

Units *

- Imperial (th)
- Imperial (in)
- Metric (um)
- Metric (mm)

Placement * ?

Total usable board area * ?

 th²

Board thickness *

 th

Total metal layers *

Layer stack-up * ?

 No file selected.

Stack-up definition * ?

Active components * ?

Passive components * ?

Total component area * ?

 th²

Number of component pins *

Number of FPGAs *

Smallest pin pitch * ?

 th

Fastest data rate (gbps) * ?

Nets testable after assembly (%) *

Test setup

- Point-to-point
- Functional (ICT)

Trace Width/Spacing

Minimum width * ?

th

Minimum spacing *

th

Typical width * ?

th

Typical spacing *

th

Via Pad/Size

Minimum hole size * ?

th

Minimum pad size *

th

Typical hole size * ?

th

Typical pad size *

th

Number of vias *

Number of nets *

Number of high-speed nets * ?

Number of voltage rails * ?

Number of ground nets *

Number of pin-to-pin connections *

Total trace distance *

th

Size of design team * ?

Design team names

Design team structure * ?

Total design time * ?

Architecture definition time (weeks) *

Schematic design time (weeks) *

Layout design time (weeks) *

Verification time (weeks) *

Manufacturing prep time (weeks) *

Did you meet the target design time? (How?) *

Standards * ?

Design validation ?

- Signal integrity analysis
- Power integrity analysis
- Thermal analysis
- Analog simulation
- Digital simulation
- RF simulation
- Manufacturability analysis
- Environmental / EMC testing
- Vibration analysis
- Analysis tools used during schematic design
- Analysis tools used during layout design

Design validation results ?

How did you collaborate with Mechanical? * ?

How did you collaborate with Manufacturing? * ?

Schematic / layout iterations *?

Layout / mechanical iterations *?

Layout / manufacturing iterations *?

Challenges *?

Tools *?

Additional comments ?

Attachments

Please attach any files related to your design. You may combine multiple files into one or attach up to three files separately. Alternatively, you can add a comment with an FTP address or request contact to upload.

File 1 *

No file selected.

File 2

No file selected.

File 3

No file selected.

Fabrication drawing *?

No file selected.

Representative image *?

No file selected.

Comments about attachments